

BEST AVAILABLE COPY

IN THE CLAIMS

Please amend claims 2-5 as follows after entry of the Examiner's Amendment submitted in the Notice of Allowance (dated April 25, 2006):

1. (Cancelled)

2. (Currently Amended). A MMIC having transistors, a RF input, a RF output, and a RF matching ~~structural~~structure, wherein said MMIC is configured to receive DC bias feed, from off the MMIC, directly at the RF matching structure; wherein said RF input is in electrical communication with said transistors, wherein said ~~transistor~~transistors are in electrical communication with said RF matching structure, and wherein said RF matching structure is in electrical communication with said RF output.

3. (Currently Amended). A MMIC having transistors, a RF input, a RF output, and a RF matching ~~structural~~structure, wherein said transistors are configured to receive one of a plurality of DC bias ~~feed~~feeds, and wherein at least one of the plurality of DC bias feeds is not received to the MMIC at the edge of the MMIC; wherein said RF input is in electrical communication with said transistors, wherein said ~~transistor~~transistors are in electrical communication with said RF matching structure, and wherein said RF matching structure is in electrical communication with said RF output.

4. (Currently Amended). A MMIC having transistors, a RF input, a RF output, and a RF matching ~~structural~~structure, wherein said RF matching structure is prepared with an ohmic material to receive said bias feed directly from off the MMIC;

BEST AVAILABLE COPY

wherein said RF input is in electrical communication with said transistors, wherein said ~~transistor~~transistors are in electrical communication with said RF matching structure, and wherein said RF matching structure is in electrical communication with said RF output.

5. (Currently Amended). A MMIC having transistors, ~~a RF input, and RF output~~ and a RF matching ~~structural~~structure; wherein said ~~transistor~~transistors and RF matching structure lie in a plane, wherein said RF matching structure is prepared with a material to receive said bias feed from a direction out of said plane of the MMIC chip; wherein said RF input is in electrical communication with said transistors, wherein said ~~transistor~~transistors are in electrical communication with said RF matching structure, and wherein said RF matching structure is in electrical communication with said RF output.

6. (Original). The MMIC of claim 5, wherein said material is at least one of an ohmic material and a metal.

7-10. (Cancelled)